



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# Analog Output MEMS Microphone Flex Evaluation Board User Guide

## GENERAL DESCRIPTION

This user guide applies to the following MEMS microphone evaluation boards:

- EV\_INMP404-FX
- EV\_INMP405-FX
- EV\_INMP504-FX
- EV\_INMP510-FX
- EV\_ICS-40180-FX
- EV\_ICS-40181-FX
- EV\_ICS-40310-FX

This is a simple evaluation board that allows quick evaluation of the performance of single-ended analog MEMS microphones. The small size and low profile of the flexible PCB enables direct placement of the microphone into a prototype or an existing design for an in situ evaluation. The evaluation board consists of a bottom port microphone soldered to a flexible PCB with color-coded wires attached. The only other component on the board is a 0.1  $\mu$ F supply bypass capacitor.

Table 1 describes the functions of the three connection wires. Table 2 describes the functional differences between the different microphones that are used with this flex circuit.

## TABLE 1. PIN FUNCTION DESCRIPTIONS

Wire Color	Microphone Pin	Description
Red	VDD	Power Supply. 1.5 V DC to 3.6 V DC; (0.9 V DC to 1.3 V DC for ICS-40310)
White	OUTPUT	Analog Output Signal
Black	GND	Ground

## TABLE 2. MICROPHONE FUNCTIONAL DIFFERENCES

Microphone	Maximum Supply Current	Maximum Output Voltage	Output Impedance	DC Offset
INMP404	250 $\mu$ A	0.18 V rms	200 $\Omega$	0.8 V
INMP405	250 $\mu$ A	0.18 V rms	200 $\Omega$	0.8 V
INMP504	225 $\mu$ A	0.18 V rms	200 $\Omega$	0.8 V
INMP510	250 $\mu$ A	0.40 V rms	350 $\Omega$	0.7 V
ICS-40180	260 $\mu$ A	0.40 V rms	350 $\Omega$	0.7 V
ICS-40181	250 $\mu$ A	0.40 V rms	350 $\Omega$	0.7 V
ICS-40310	25 $\mu$ A	0.12 V rms	4.5 k $\Omega$	0.57 V

## EVALUATION BOARD CIRCUIT

Figure 1 shows the schematic of the evaluation board, and Figure 2 shows the flex board layout. See the respective microphone data sheets for complete descriptions and specifications of the microphones. Note that the layout for the EV\_ICS-40181-FX differs slightly from what is shown in Figure 2 because of this part's different package footprint, but the routing of the three signals is consistent.

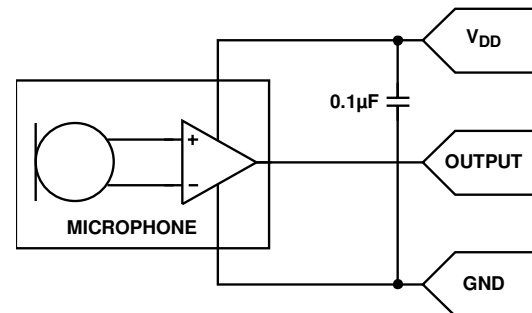


Figure 1. Evaluation Board Schematic

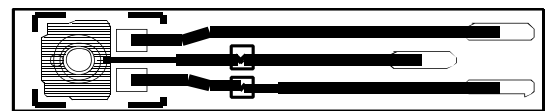
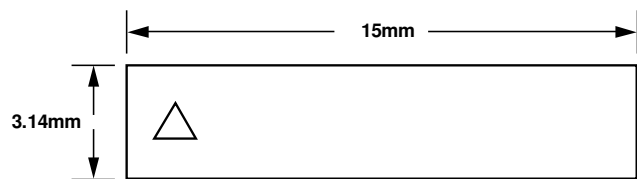
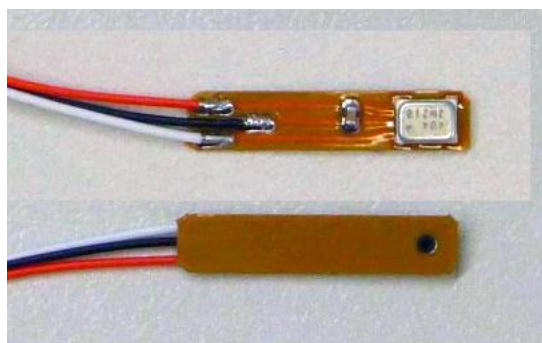


Figure 2. Evaluation Board Layout (Top View)



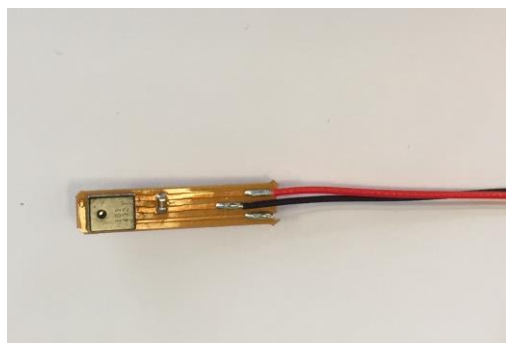
**Figure 3. Evaluation Board Dimensions in Millimeters (Wires Not Included)**

**BOTTOM PORT EVALUATION BOARD PHOTOGRAPH**



**Figure 4. Top and Bottom View**

**TOP PORT EVALUATION BOARD PHOTOGRAPH**



**Figure 5. Top View**

**REVISION HISTORY**

REVISION DATE	REVISION	DESCRIPTION
10/14/2015	1.3	This v1.3 is the initial release in Agile. Previous revisions were uncontrolled.
03/26/2015	1.4	Updated part names, added Figure 5

**COMPLIANCE DECLARATION DISCLAIMER**

InvenSense believes the environmental and other compliance information given in this document to be correct but cannot guarantee accuracy or completeness. Conformity documents substantiating the specifications and component characteristics are on file. InvenSense subcontracts manufacturing and the information contained herein is based on data received from vendors and suppliers, which has not been validated by InvenSense.

This information furnished by InvenSense is believed to be accurate and reliable. However, no responsibility is assumed by InvenSense for its use, or for any infringements of patents or other rights of third parties that may result from its use. Specifications are subject to change without notice. InvenSense reserves the right to make changes to this product, including its circuits and software, in order to improve its design and/or performance, without prior notice. InvenSense makes no warranties, neither expressed nor implied, regarding the information and specifications contained in this document. InvenSense assumes no responsibility for any claims or damages arising from information contained in this document, or from the use of products and services detailed therein. This includes, but is not limited to, claims or damages based on the infringement of patents, copyrights, mask work and/or other intellectual property rights.

Certain intellectual property owned by InvenSense and described in this document is patent protected. No license is granted by implication or otherwise under any patent or patent rights of InvenSense. This publication supersedes and replaces all information previously supplied. Trademarks that are registered trademarks are the property of their respective companies. InvenSense sensors should not be used or sold in the development, storage, production or utilization of any conventional or mass-destructive weapons or for any other weapons or life threatening applications, as well as in any other life critical applications such as medical equipment, transportation, aerospace and nuclear instruments, undersea equipment, power plant equipment, disaster prevention and crime prevention equipment.

©2015 InvenSense, Inc. All rights reserved. InvenSense, MotionTracking, MotionProcessing, MotionProcessor, MotionFusion, MotionApps, DMP, AAR, and the InvenSense logo are trademarks of InvenSense, Inc. Other company and product names may be trademarks of the respective companies with which they are associated.



©2015 InvenSense, Inc. All rights reserved.